

Amendments to the Claims

This listing of claims will replace all previous versions and listing of claims.

Listing of Claims

1. (Currently Amended) A solder composition made of a uniform mixture of a liquid substance and solder particles; wherein

the liquid substance is a fatty acid ester and comprises a flux component which reacts at a melting point of the solder particles;

the mixture of the liquid substance and solder particles has a viscosity that flows at room temperature and deposits in layers on a base material; and

the solder particles are mixed in the liquid substance at room temperature, and are granular agents that precipitate in the liquid substance towards the base material, having a mixing ratio and a particle diameter to be uniformly dispersible within the liquid substance,

wherein the mixing ratio of the solder particles is less than or equal to 30wt%.

2.-8. (Canceled)

9. (Currently Amended) The solder composition as claimed in claim 8, wherein the flux component is a free fatty acid contained in the ~~fat~~ liquid substance.

10. (Canceled)

11. (Currently Amended) The solder composition as claimed in claim ~~10~~ 1, wherein the fatty acid ester is neopentylpolyolester.

12. (Currently Amended) The solder composition as claimed in claim ~~8~~ 1, wherein an acid value of the ~~fat~~ fatty acid ester is greater than or equal to one.

13. (Previously Presented) A method of forming bumps comprising:

deposition for depositing on a base material a solder composition comprising a mixture of solder particles and a liquid substance with flux component whose reaction temperature is close to the melting point of the solder particles, the solder composition having a viscosity that flows at normal temperature and that deposits in layers on a base material, and solder particles that precipitate through the liquid substance towards the base material and that have a mixing ratio and a particle diameter to be uniformly dispersible within the liquid substance; and

reflow step for heating the solder composition and forming bumps made up of solder particles on the base material,

wherein the solder particles are uniformly dispersed in the liquid substance by stirring the solder composition in a pre-stage of the deposition; and

wherein the mixing ratio of the solder particles is less than or equal to 30wt%.

14. (Canceled)

15. (Original) The method of forming bumps as claimed in claim 13, wherein the solder composition is spin coated to a uniform thickness by rotating the base material in the deposition step.

16. (Original) The method of forming bumps as claimed in claim 13, wherein the solder composition is poured into a container arranged with the base material, and the base material is immersed in the solder composition in the deposition step.

17. (Previously Presented) A solder composition made of a uniform mixture of a liquid substance and solder particles; wherein

the liquid substance comprises a flux component which reacts at a melting point of the solder particles;

the mixture of the liquid substance and solder particles has a viscosity that flows at a normal temperature and deposits in layers on a base material;

the solder particles are mixed in the liquid substance at room temperature, and are granular agents that precipitate in the liquid substance towards the base material, having a mixing ratio and a particle diameter to be uniformly dispersible within the liquid substance; and

the particle diameter of the solder particles is 35 μm or less.

18. (Previously Presented) A method of forming bumps comprising:

deposition step for depositing on a base material a solder composition including a mixture of solder particles and a liquid substance with flux component whose reaction temperature is close to the melting point of the solder particles, having a viscosity that flows at normal temperature and that deposits in layers on a base material, and solder particles that precipitate through the liquid substance towards the base material and that have a mixing ratio and a particle diameter to be uniformly dispersible within the liquid substance; and

reflow step for heating the solder composition and forming bumps made up of solder particles on the base material, wherein

in the deposition, the particle diameter of the solder particle is set to be 35 μm or less.

19. (New) A solder composition consisting essentially of:

a liquid substance;

solder particles; and optionally

a flux component.

20. (New) The solder composition according to claim 19, wherein the liquid substance is a fat.

21. (New) The solder composition according to claim 20, wherein the fat is fatty acid ester.

22. (New) The solder composition according to claim 21, wherein the fatty acid ester is neopentylpolyolester.

23. (New) The solder composition according to claim 19, including a flux component that is an acid.

24. (New) The solder composition according to claim 23, wherein the flux component is an organic acid.

25. (New) The solder composition according to claim 24, wherein the flux component is a fatty acid.

26. (New) The solder composition according to claim 19, wherein the liquid substance is a fat and the solder composition includes the flux component, which is a fatty acid.

27. (New) The solder composition according to claim 26, wherein the fat is a fatty acid ester.

28. (New) The solder composition according to claim 27, wherein the fatty acid ester is neopentylpolyolester.